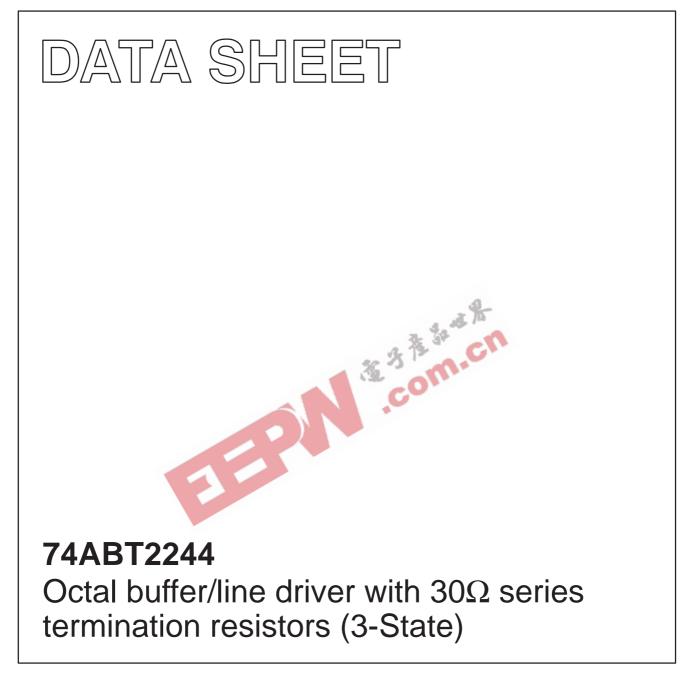
INTEGRATED CIRCUITS



Product specification Supersedes data of 1996 Oct 23 IC23 Data Handbook

1998 Jan 16



74ABT2244

FEATURES

- Octal bus interface
- 3-State buffers
- Live insertion/extraction permitted
- Outputs include series resistance of 30Ω, making external termination resistors unnecessary
- Output capability: +5mA/-32mA
- Latch-up protection exceeds 500mA per Jedec Std 17
- ESD protection exceeds 2000 V per MIL STD 883 Method 3015 and 200 V per Machine Model
- Power-up 3-State
- Same part as 74ABT244-1
- Inputs are disabled during 3-State mode

DESCRIPTION

The 74ABT2244 high-performance BiCMOS device combines low static and dynamic power dissipation with high speed.

The 74ABT2244 device is an octal buffer that is ideal for driving bus lines. The device features two Output Enables (10E, 20E), each controlling four of the 3-State outputs.

The 74ABT2244 is designed with 30Ω series resistance in both the High and Low states of the output. This design reduces line noise in applications such as memory address drivers, clock drivers and bus receivers/transmitters.

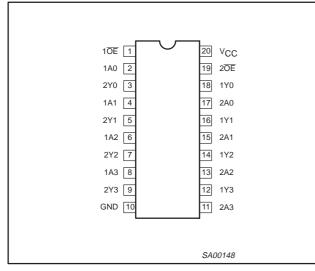
The 74ABT2244 is the same as the 74ABT244-1. The part number has been changed to reflect industry standards.

SYMBOL	PARAMETER	CONDITIONS $T_{amb} = 25^{\circ}C; GND = 0V$	TYPICAL	UNI
t _{PLH} t _{PHL}	Propagation delay An to Yn	C _L = 50pF; V _{CC} = 5V	2.8 3.9	ns
C _{IN}	Input capacitance	$V_i = 0V$ or V_{CC}	4	pF
C _{OUT}	Output capacitance	Outputs disabled; $V_0 = 0V$ or V_{CC}	7	pF
I _{CCZ}	Total supply current	Outputs disabled; V _{CC} = 5.5V	50	μΑ

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
20-Pin Plastic DIP	-40°C to +85°C	74ABT2244 N	74ABT2244 N	SOT146-1
20-Pin plastic SO	–40°C to +85°C	74ABT2244 D	74ABT2244 D	SOT163-1
20-Pin Plastic SSOP Type II	–40°C to +85°C	74ABT2244 DB	74ABT2244 DB	SOT339-1
20-Pin Plastic TSSOP Type I	-40°C to +85°C	74ABT2244 PW	7ABT2244PW DH	SOT360-1

PIN CONFIGURATION

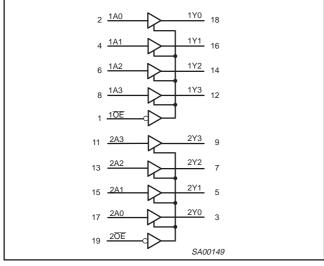


PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION
2, 4, 6, 8	1A0 – 1A3	Data inputs
11, 13, 15, 17	2A0 – 2A3	Data inputs
18, 16, 14, 12	1Y0 – 1Y3	Data outputs
9, 7, 5, 3	2Y0 – 2Y3	Data outputs
1, 19	10E, 20E	Output enables
10	GND	Ground (0V)
20	V _{CC}	Positive supply voltage

74ABT2244

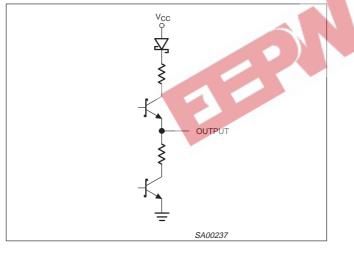
LOGIC SYMBOL



1 ΕN 2 18 \triangleright ∇ 4 16 6 14 8 12 19 ΕN 9 11 ∇ \triangleright 7 13 5 15 3 SA00150 3

LOGIC SYMBOL (IEEE/IEC)

SCHEMATIC OF EACH OUTPUT



FUNCTION TABLE

C	INP	UTS		OUTF	PUTS
10E	1An	2 0E	2An	1Yn	2Yn
L	L	L	L	L	L
L	н	L	н	н	н
н	х	н	х	Z	Z

High voltage level Н =

L Low voltage level =

X Z = Don't care

= High impedance "off" state

74ABT2244

ABSOLUTE MAXIMUM RATINGS^{1, 2}

SYMBOL	PARAMETER	PARAMETER CONDITIONS				
V _{CC}	DC supply voltage		-0.5 to +7.0	V		
I _{IK}	DC input diode current	V ₁ < 0	-18	mA		
VI	DC input voltage ³		-1.2 to +7.0	V		
I _{OK}	DC output diode current	V _O < 0	-50	mA		
V _{OUT}	DC output voltage ³	output in Off or High state	-0.5 to +5.5	V		
I _{OUT}	DC output current	output in Low state	128	mA		
T _{stg}	Storage temperature range		–65 to 150	°C		

NOTES:

1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction

2.

temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C. 3. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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SYMBOL	PARAMETER	LIM	UNIT	
STMBOL	PARAMETER	Min	Max	UNIT
V _{CC}	DC supply voltage	4.5	5.5	V
VI	Input voltage	0	V _{CC}	V
V _{IH}	High-level input voltage	2.0		V
V _{IL}	Low-level Input voltage		0.8	V
I _{ОН}	High-level output current		-32	mA
I _{OL}	Low-level output current		12	mA
Δt/Δv	Input transition rise or fall rate	0	5	ns/V
T _{amb}	Operating free-air temperature range	-40	+85	°C

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RECOMMENDED OPERATING CONDITIONS

74ABT2244

DC ELECTRICAL CHARACTERISTICS

					LIMITS			
SYMBOL	PARAMETER TEST CONDITIONS		T _{ar}	_{nb} = +25	°C		: –40°C 85°C	UNIT
			Min	Тур	Max	Min	Max	
V _{IK}	Input clamp voltage	$V_{CC} = 4.5V; I_{IK} = -18mA$		-0.9	-1.2		-1.2	V
		V_{CC} = 4.5V; I_{OH} = -3mA; V_I = V_{IL} or V_{IH}	2.5	2.9		2.5		V
V _{OH}	High-level output voltage	V_{CC} = 5.0V; I_{OH} = –3mA; V_{I} = V_{IL} or V_{IH}	3.0	3.4		3.0		V
		V_{CC} = 4.5V; I_{OH} = -32mA; V_I = V_{IL} or V_{IH}	2.0	2.4		2.0		V
Vol	Low-level output voltage	V_{CC} = 4.5V; I_{OL} = 5mA; V_I = V_{IL} or V_{IH}		0.32	0.55		0.55	V
VOL	Low-level output voltage	V_{CC} = 4.5V; I_{OL} = 12mA; V_{I} = V_{IL} or V_{IH}			0.8		0.8	V
l _l	Input leakage current	$V_{CC} = 5.5V; V_I = GND \text{ or } 5.5V$		±0.01	±1.0		±1.0	μΑ
I _{OFF}	Power-off leakage current	V_{CC} = 0.0V; V_{O} or $V_{I} \leq 4.5V$		5.0	100		100	μΑ
I _{PU/PD}	Power-up/down 3-State output current ³	$V_{CC} = 2.1V; V_O = 0.5V; V_I = GND \text{ or } V_{CC}; V_{OE} = Don't \text{ care}$	S. A	5.0	50		50	μΑ
I _{OZH}	3-State output High current	V_{CC} = 5.5V; V_{O} = 2.7V; V_{I} = V_{IL} or V_{IH}	-	0.1	50		50	μΑ
I _{OZL}	3-State output Low current	V_{CC} = 5.5V; V_{O} = 0.5V; V_{I} = V_{IL} or V_{IH}		-0.1	-50		-50	μA
I _{CEX}	Output High leakage current	V_{CC} = 5.5V; V_{O} = 5.5V; V_{I} = GND or V_{CC}		5.0	50		50	μΑ
lo	Output current ¹	$V_{CC} = 5.5V; V_0 = 2.5V$	-50	-100	-180	-50	-180	mA
Іссн		V_{CC} = 5.5V; Outputs High, V_{I} = GND or V_{CC}		50	250		250	μA
I _{CCL}	Quiescent supply current	V_{CC} = 5.5V; Outputs Low, V_1 = GND or V_{CC}		24	30		30	mA
I _{CCZ}		V_{CC} = 5.5V; Outputs 3-State; V _I = GND or V _{CC}		50	250		250	μΑ
		Outputs enabled, one input at 3.4V, other inputs at V_{CC} or GND; $V_{CC} = 5.5V$		0.5	1.5		1.5	mA
ΔI _{CC}	Additional supply current per input pin ²	Outputs 3-State, one enable input at 3.4V, other inputs at V_{CC} or GND; $V_{CC} = 5.5V$		50	250		250	μA
		Outputs 3-State, one enable input at 3.4V, other inputs at V_{CC} or GND; V_{CC} = 5.5V		0.5	1.5		1.5	mA

NOTES:

1. Not more than one output should be tested at a time, and the duration of the test should not exceed one second. 2. This is the increase in supply current for each input at 3.4V. 3. This parameter is valid for any V_{CC} between 0V and 2.1V, with a transition time of up to 10msec. From $V_{CC} = 2.1V$ to $V_{CC} = 5V \pm 10\%$ a transition time of up to 100µsec is permitted.

AC CHARACTERISTICS

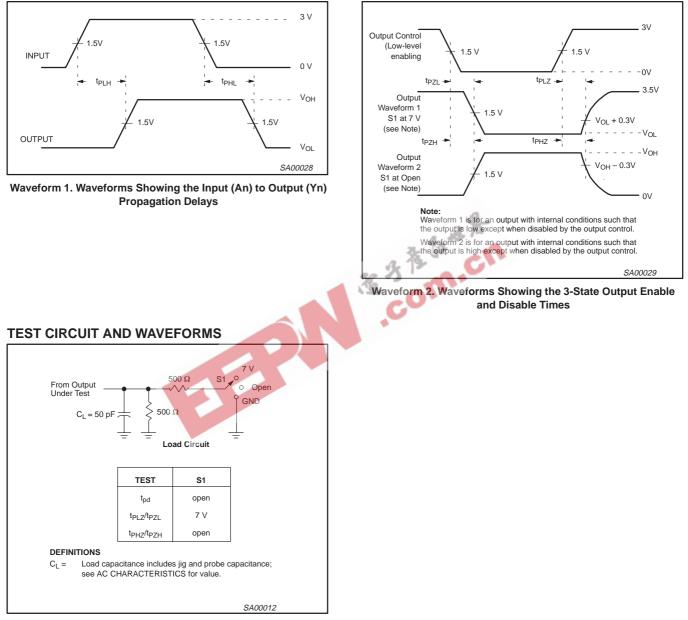
GND = 0V; $t_R = t_F$ = 2.5ns; C_L = 50pF, R_L = 500 Ω

					LIMI	ſS		
SYMBOL	PARAMETER	WAVEFORM	T _é V	amb = +25° ′CC = +5.0′	C V	$T_{amb} = -40^{\circ}$ $V_{CC} = +5.$	°C to +85°C .0V ±0.5V	UNIT
			Min	Тур	Max	Min	Max	
t _{PLH} t _{PHL}	Propagation delay An to Yn	1	1.0 1.0	2.8 3.9	4.3 5.3	1.0 1.0	4.7 5.6	ns
t _{PZH} t _{PZL}	Output enable time to High and Low level	2	1.1 2.1	3.3 5.0	4.8 7.3	1.1 2.1	5.5 8.3	ns
t _{PHZ} t _{PLZ}	Output disable time from High and Low level	2	2.1 1.7	3.7 3.4	5.6 5.3	2.1 1.7	6.6 5.8	ns

74ABT2244

AC WAVEFORMS

 V_{M} = 1.5V, V_{IN} = GND to 3.0V



SOT146-1 M_E seating plane \square -l_{b1} b₁ (e ₁ 11 20 M_H pin 1 index 10 10 mm 5 scale

DIP20: plastic dual in-line package; 20 leads (300 mil)

DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	с	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	L	ME	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.0
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

VERSION IEC JEDEC EIAJ PROJECTION	OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE
	VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
$1 - SC603 - 1 - H_{+}H_{+}H_{-}$	SOT146-1			SC603		-92-11-17- 95-05-24

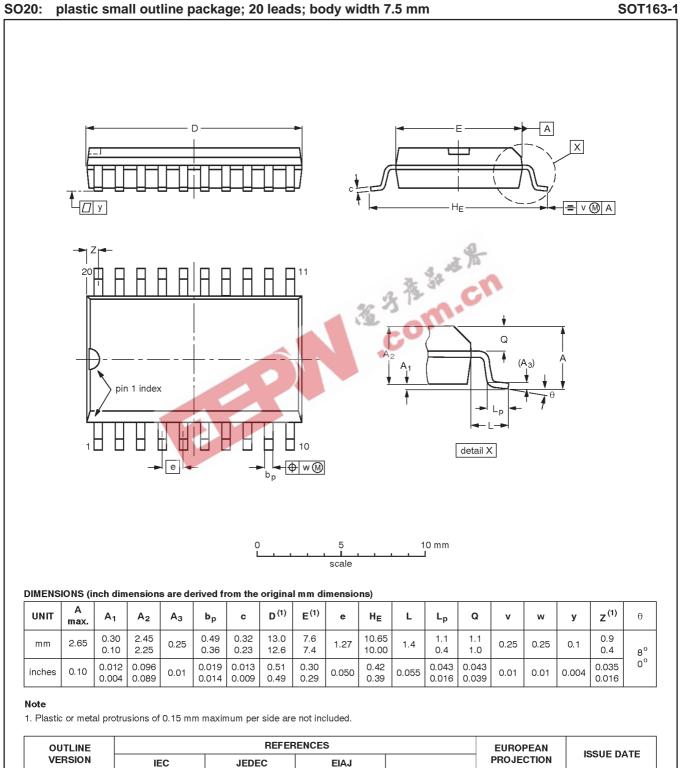


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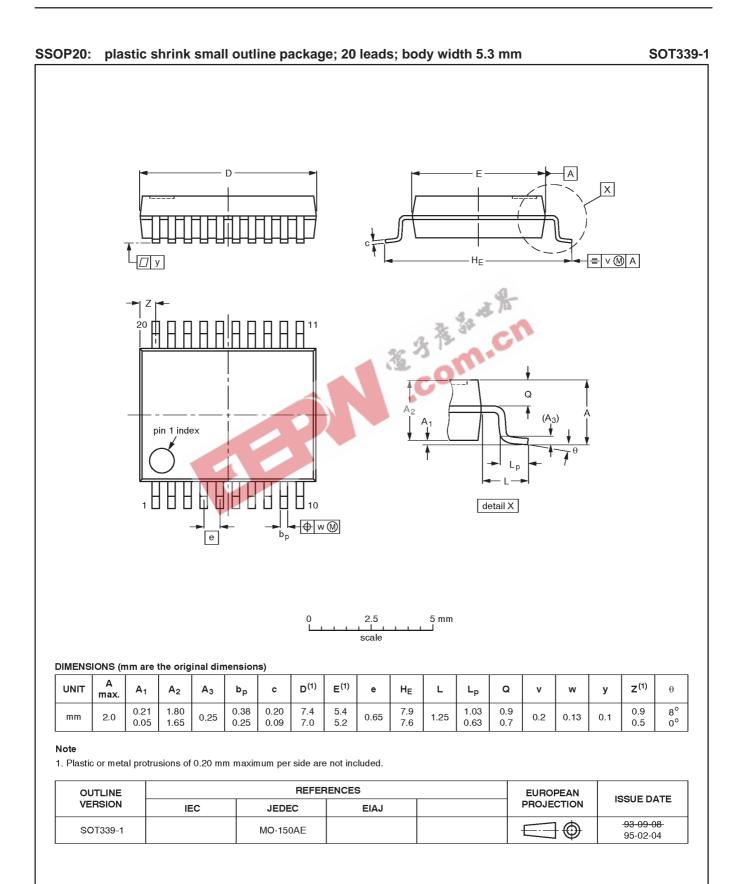


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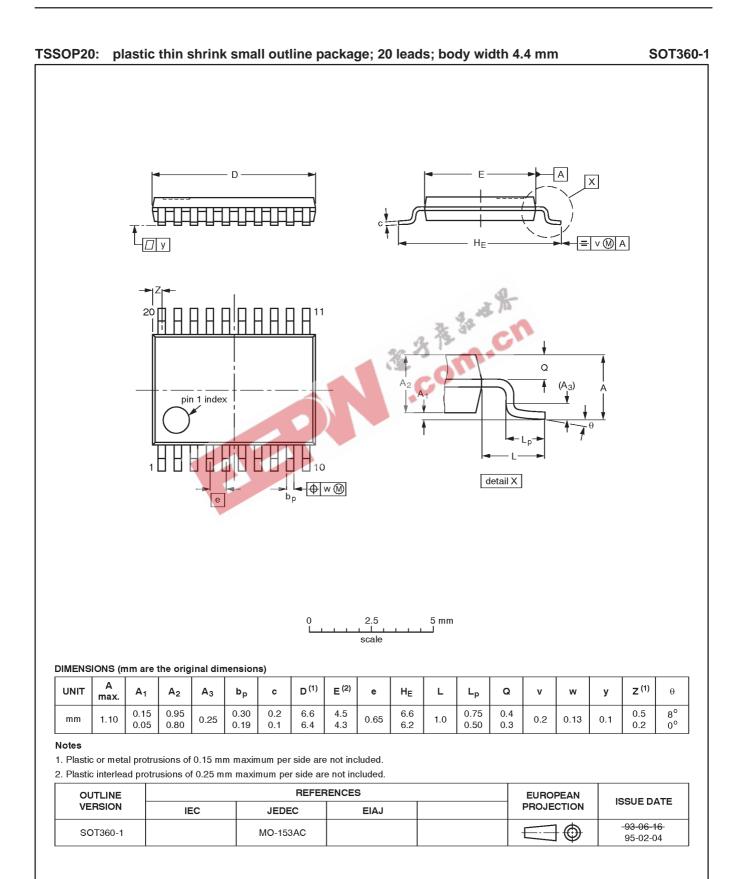
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74ABT2244

NOTES



Product specification

74ABT2244

Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
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[1] Please consult the most recently issued datasheet before initiating or completing a design.

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Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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